



SOT1039-2

HXQFN16 (U) plastic thermal enhanced extremely thin quad flat package; no leads; 16 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.5 mm body

3 November 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HXQFN16(U)
Package type industry code	HXQFN16(U)
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-3-2011
Manufacturer package code	SOT1039-2

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	16	-	A/A



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2. Package outline

HXQFN16 (U): plastic thermal enhanced extremely thin quad flat package; no leads; 16 terminals; body 3 x 3 x 0.5 mm

SOT1039-2

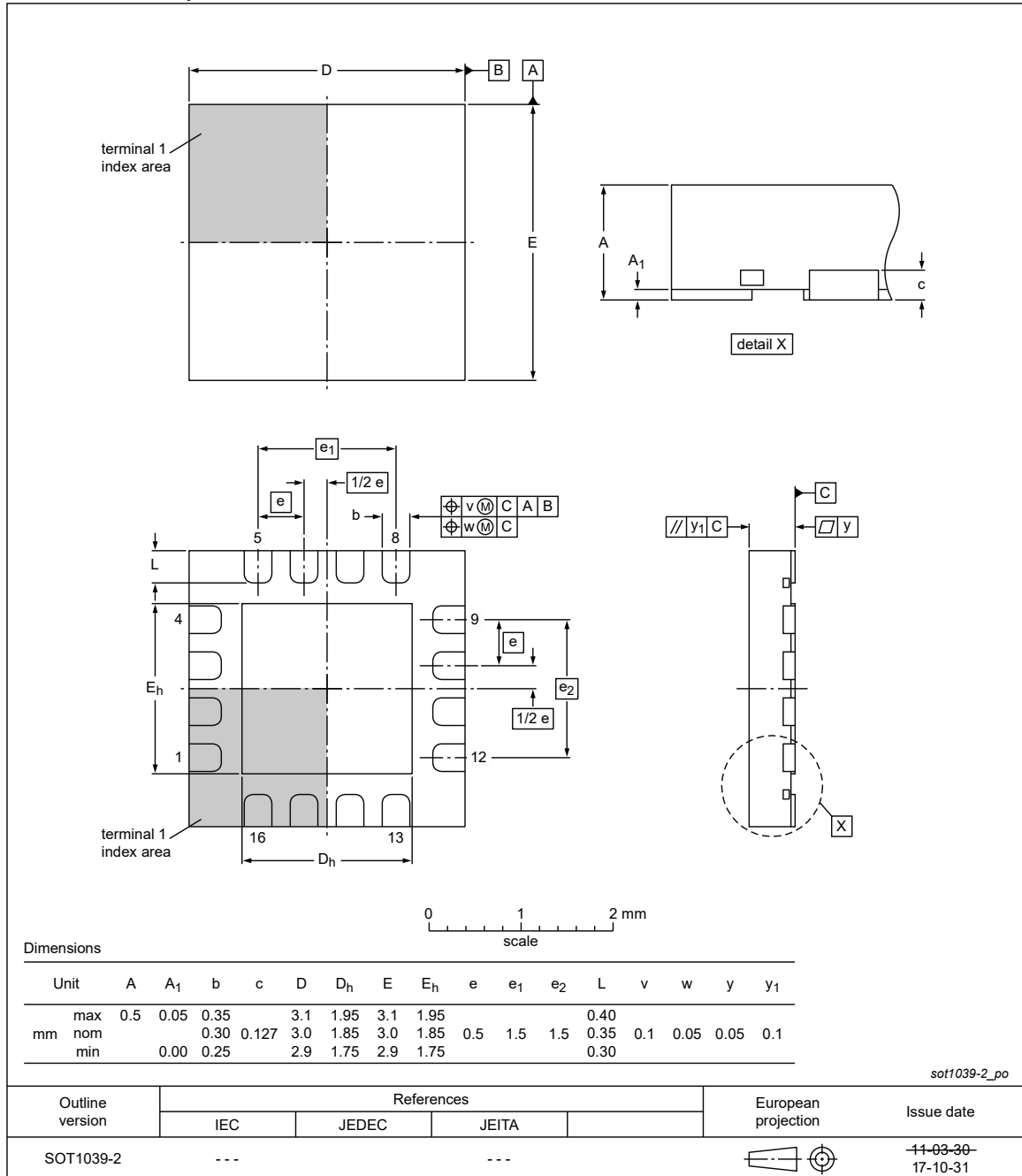


Fig. 1. Package outline HXQFN16(U) (SOT1039-2)

3. Soldering

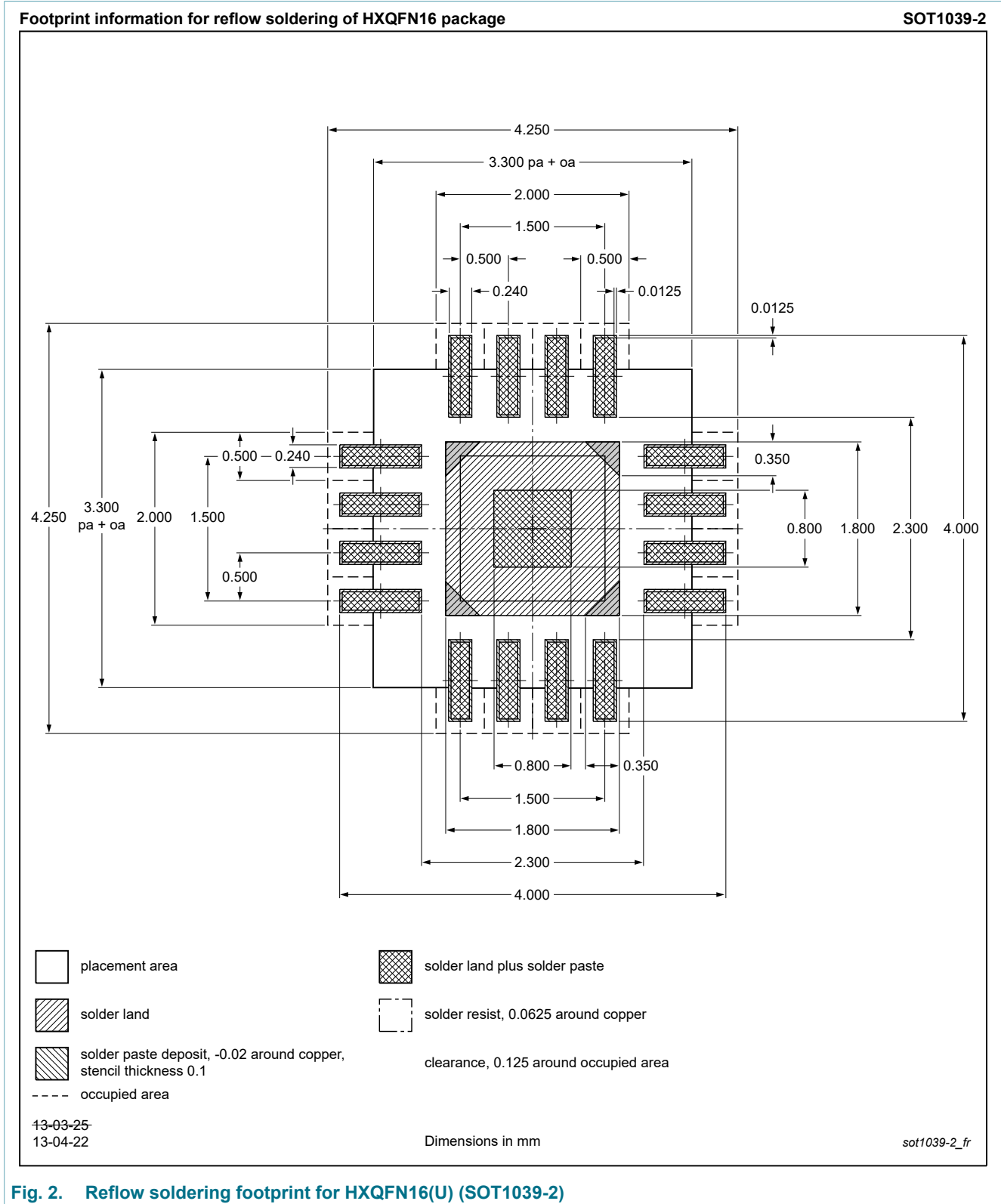


Fig. 2. Reflow soldering footprint for HXQFN16(U) (SOT1039-2)

HXQFN16 (U) plastic thermal enhanced extremely thin quad flat package; no leads; 16 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.5 mm body

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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Date of release: 3 November 2017
